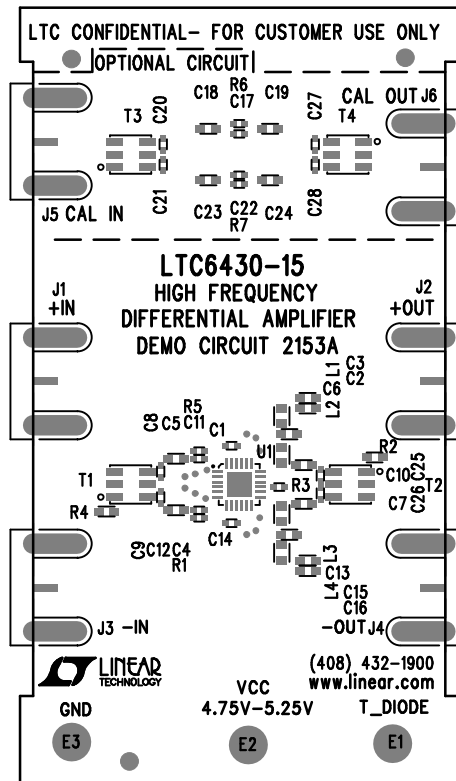
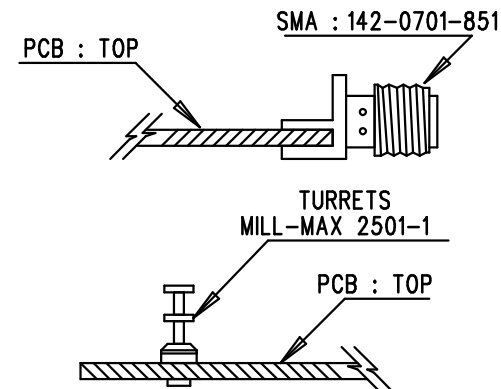


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	1	1ST PROTOTYPE	JOHN C.	11-05-13
-	1	PRODUCTION	JOHN C.	12-13-13

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. NO SHUNT.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL SMA CONNECTORS AND TURRETS AS SHOWN BELOW:



TOP SILKSCREEN
LINEAR TECHNOLOGY
DATE: 11-05-13
DC2153A-1, LTC6430-15
HIGH FREQUENCY
DIFFERENTIAL AMPLIFIER

APPROVALS

PCB DES. AK.
APP ENG. JOHN C.



1630 MCCARTHY BLVD
MILPITAS, CA 95035
PH: (408)432-1900
www.linear.com
LTC CONFIDENTIAL-
FOR CUSTOMER USE ONLY

TITLE: TOP ASSEMBLY DRAWING

HIGH FREQUENCY DIFFERENTIAL AMPLIFIER

SIZE N/A IC NO. LTC6430AIUF-15
N/A DEMO CIRCUIT 2153A REV. 1

SCALE = NONE

FILENAME: DC2153A-1.PCB

SHT 1 OF 1